

WireChar Multiphysical characterization of advanced superconductors

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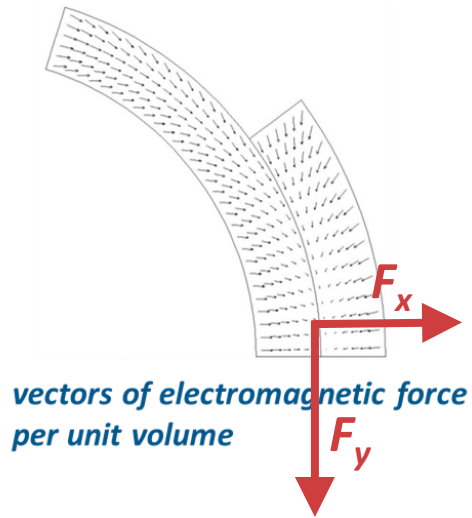
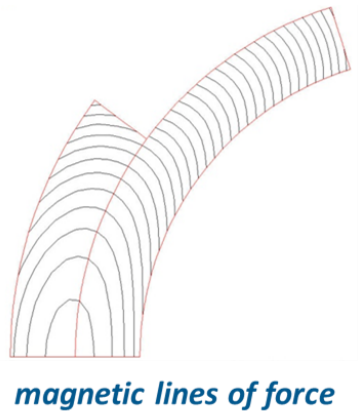
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Outline

- **Motivation of the work**
 - Strain sensitivity and stress management in accelerator magnets based on Nb₃Sn
- **Overview of the wire testing facilities at UNIGE**
 - Focus on the properties relevant for magnet design
- **Irreversible reduction of the critical current under mechanical loads**
 - A combination of electromechanical tests, X-ray microtomography with deep learning and FE simulations to identify the dominant mechanism behind the degradation
- **Summary and conclusions**

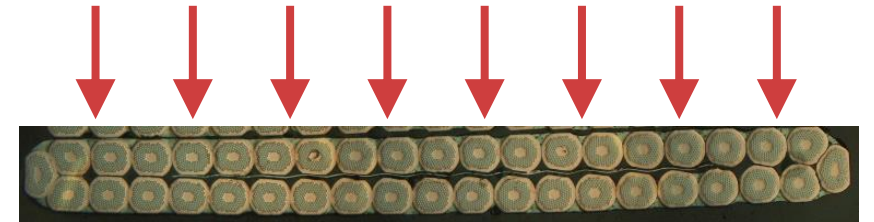
Stress management is key for Nb₃Sn-based accelerator magnets



The projects of the 11 T dipoles and the MQXF quadrupoles for the high luminosity upgrade of LHC provide very relevant experience on the use of Nb₃Sn conductors for accelerator magnets

All design options developed for the 16 T dipoles for a future 100 TeV collider share a peak stress in the range of 150-200 MPa at operation

The most severe electromagnetic loads are those acting in the transverse direction of the Nb₃Sn Rutherford cables



The brittleness of Nb₃Sn combined with huge electromagnetic forces, thermomechanical effects and tight tolerances and make easy to exceed the mechanical limits of the conductor and degrade the magnet performance

What is a safe maximum transverse stress limit to consider as magnet design criterion?

Overview of the wire testing facilities at UNIGE

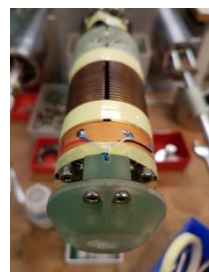
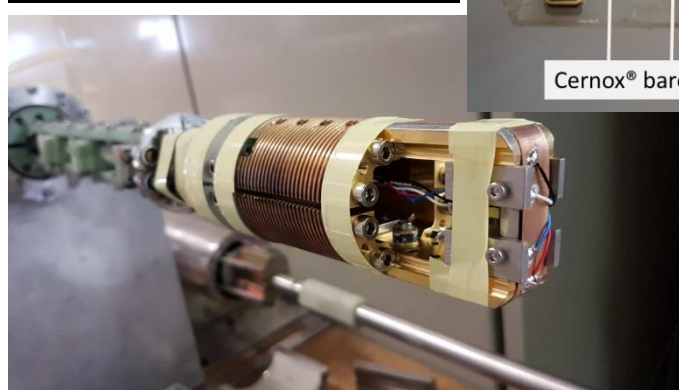
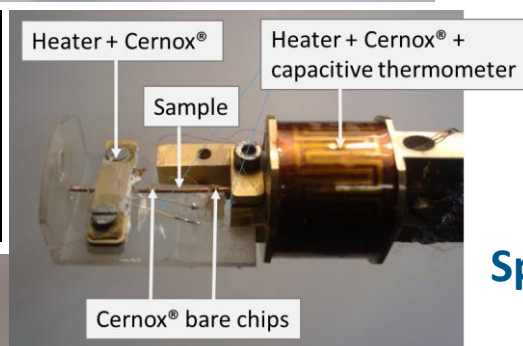
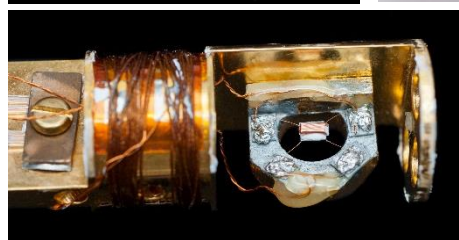
High-Field Low-Temperature characterization of LTS and HTS for applications



The laboratory at UNIGE is equipped with a **19 T/ 21 T magnet** with a **50 mm** variable temperature insert

UNIGE has also developed **custom setups** for the measurement of **properties relevant for magnet design**:

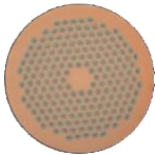


- Critical current versus **longitudinal strain** (Walters spiral, aka WASP), up to 1 kA
- Critical current versus **transverse stress** (compressive WASP), up to 1 kA, 40 kN
- **Thermophysical properties** (heat capacity, thermal conductivity)



Specially developed for HTS characterization:

- Critical current versus magnetic field **up to 2 kA at 4.2 K**, up to 1 kA **in gas flow** (active stabilization of the temperature)
- Possibility to measure long samples at **various field orientations** (testing the anisotropy of HTS)

What has been tested – Catalogue of the Wires

	Technology	# of subelements	Cu/non-Cu	Subelement size/shape	Diameter	$I_c(16\text{ T})$	Wire ID	
	PIT	192	1.22	50 μm round	1.0 mm	340 A	#0904 #31712 #14310	} FRESCA-2
				43 μm round	0.85 mm	240 A	#29992	
	RRP	108/127	1.2	~55 μm	0.85 mm	280 A	#14753 #14516 (Ta) #76A08U #A02U4014 #271A05	} MQXF
				~45 μm	0.7 mm	160 A	#073A02 #271A05	
	RRP	132/169	1.2	~60 μm	1.0 mm	370 A	#15114 #114163	} 11 T
				~50 μm	0.85 mm	245 A	#14393	

L. Gämperle, *et al.*, Phys. Rev. Research **2** (2020) 013211 DOI: [10.1103/PhysRevResearch.2.013211](https://doi.org/10.1103/PhysRevResearch.2.013211)

J. Ferradas Troitino, *et al.*, Supercond. Sci. Technol., **34** (2021) 035008 DOI: [10.1088/1361-6668/abd388](https://doi.org/10.1088/1361-6668/abd388)

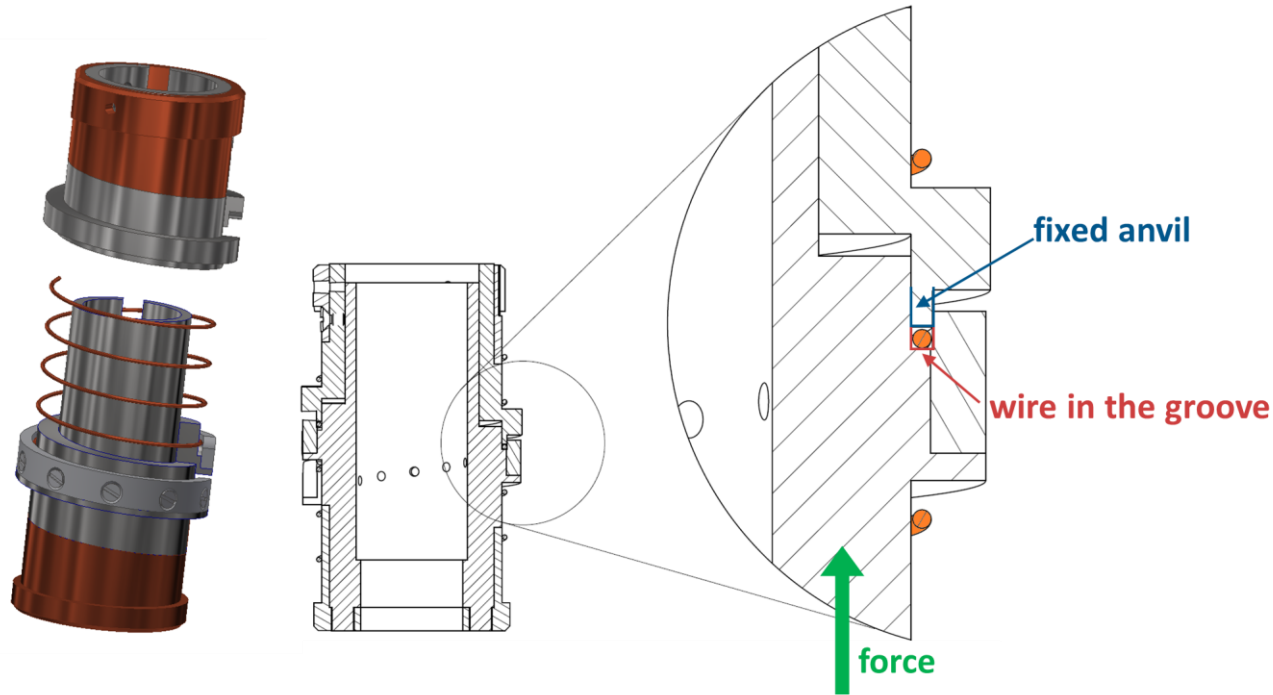
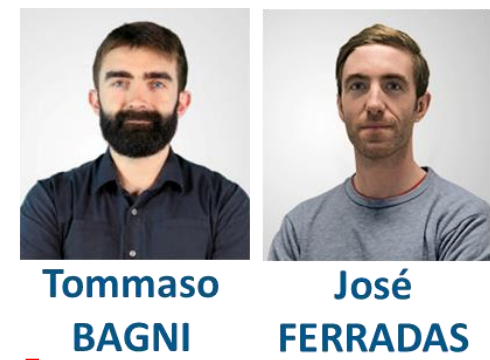
What has been tested

A comprehensive campaign of **electromechanical tests** to gain knowledge on some very practical aspects

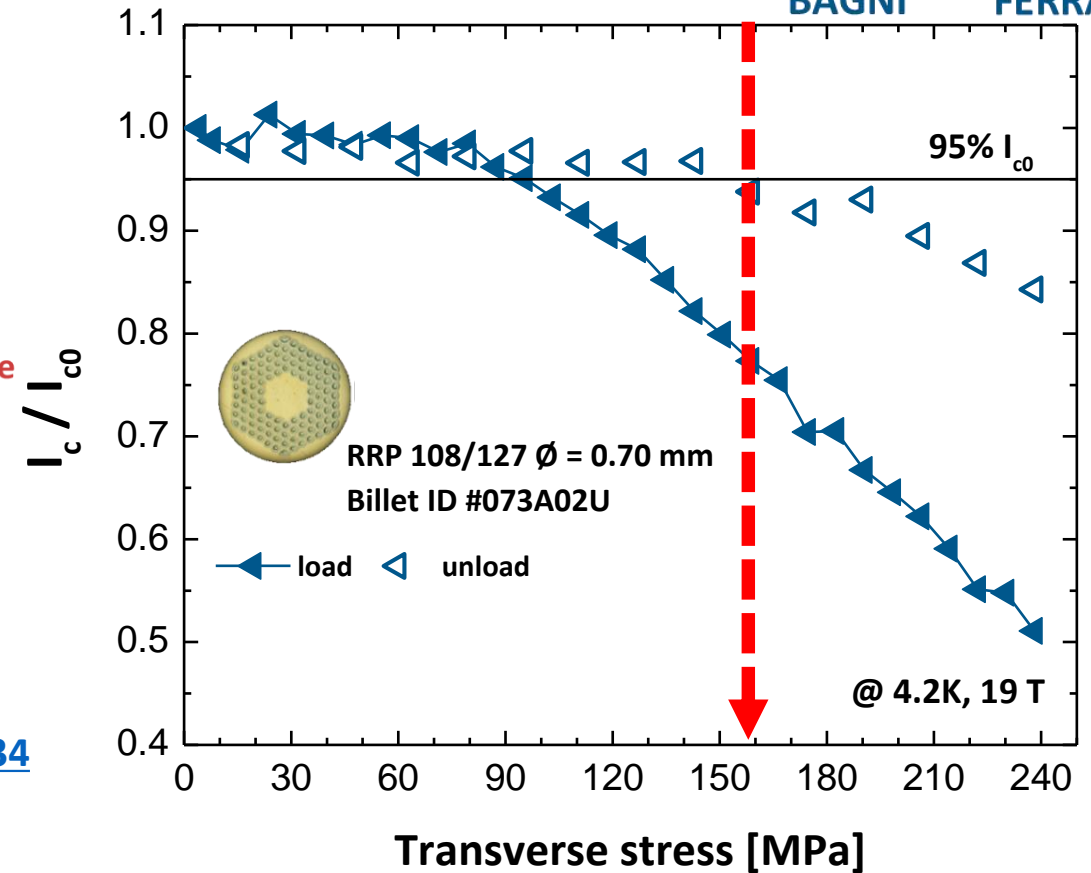
- Probed the **impact** of the **impregnation scheme** on the transverse stress tolerance
Quantified the effect of the rigidity of the impregnation on the irreversible stress limit of PIT wires
- Assessed the effect of the **longitudinal strain state** on the **response to transverse stress**
Investigated RRP wires under longitudinal and transverse loads
- Investigated the **impact** of the wire **deformation during cabling** on the transverse stress tolerance
Performed measurements on PIT and RRP wires, round and 15%-rolled to simulate the effects of cabling
- Assessed the **basic mechanism behind the degradation** of the critical current under transverse loads

Tolerance to transverse stress of a single wire

Electromechanical tests on Nb₃Sn wires impregnated with epoxy



The WASP concept was adapted to transverse loads by
B. Seeber et al., IEEE TAS 17 (2007) 2643, DOI: [10.1109/TASC.2007.897934](https://doi.org/10.1109/TASC.2007.897934)



The **irreversible limit** is defined at the force level leading to a **95% recovery of the initial I_c** after unload

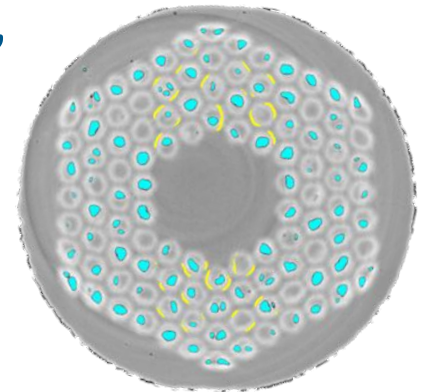
Here the irreversible stress limit is σ_{irr} (B=19T)= **155 MPa** (force dived by groove area)

Degradation mechanisms and irreversible reduction of I_c

Two mechanisms govern the irreversible reduction of the critical current

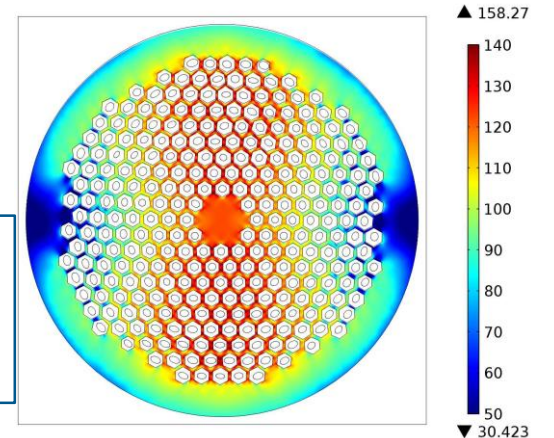
- Formation of **cracks** in the Nb_3Sn filaments due, for instance, to the stress concentration at the voids

Cracks generate a reduction of the current carrying cross section $\Rightarrow I_c^{unload}/I_{c0}$ is independent of the magnetic field



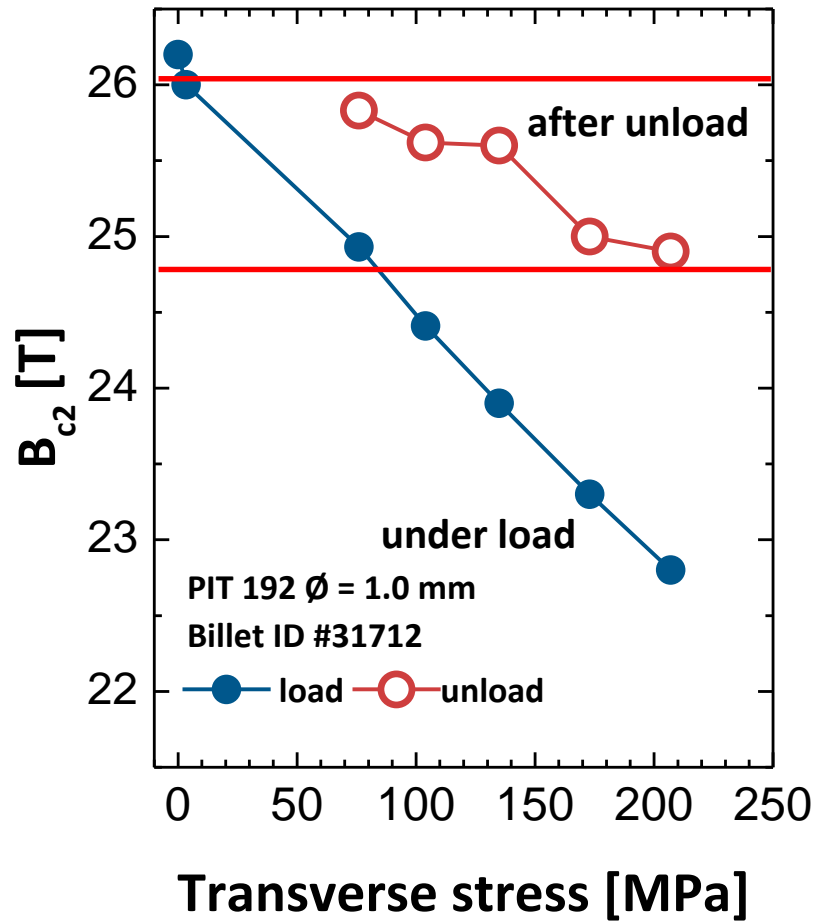
- Plastic deformation** of the matrix and residual stress on the Nb_3Sn filaments

Residual stress induces a permanent reduction of B_{c2} after unload $\Rightarrow I_c^{unload}/I_{c0}$ depends on of the magnetic field

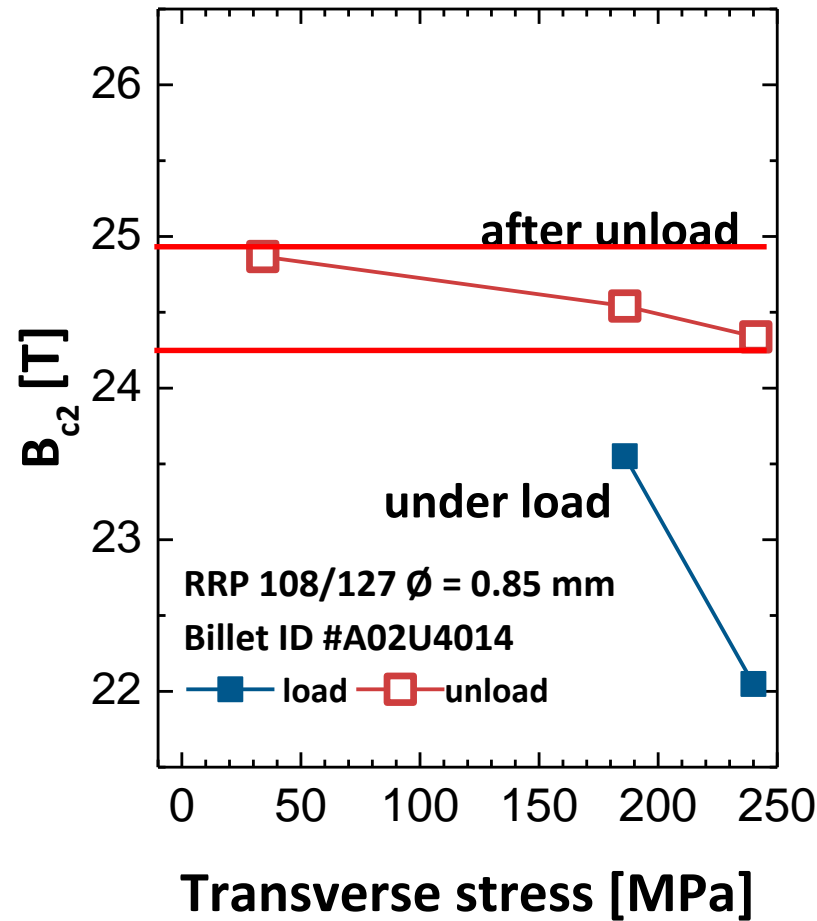


Comparison of B_{c2} under load and after unload

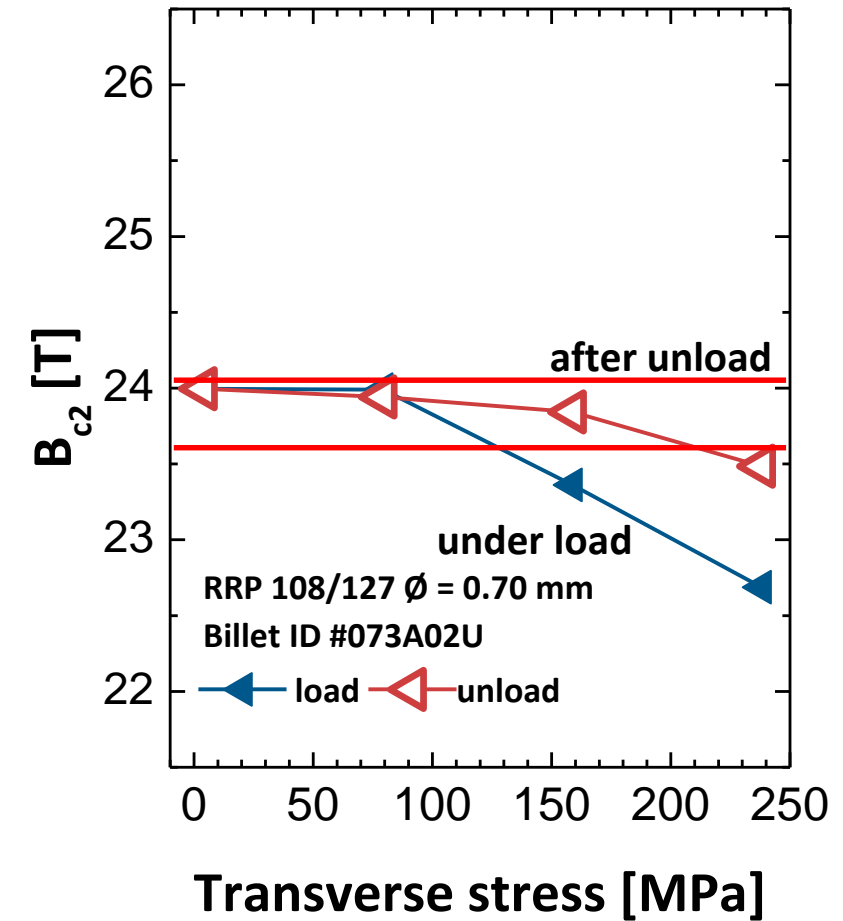
PIT, $\varnothing = 1.0$ mm



RRP, $\varnothing = 0.85$ mm



RRP, $\varnothing = 0.7$ mm



After unload from $\sigma = 210$ MPa

$$\Delta B_{c2}^{\text{unload}} \approx 1 \text{ T}$$

After unload from $\sigma = 240$ MPa

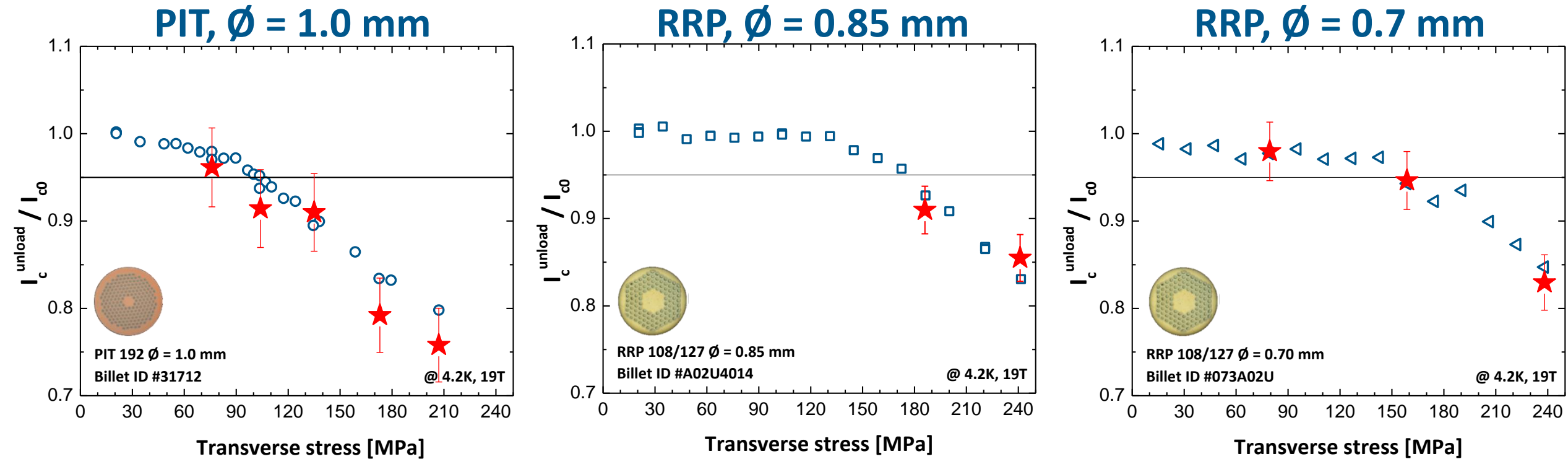
$$\Delta B_{c2}^{\text{unload}} \approx 0.5 \text{ T}$$

After unload from $\sigma = 240$ MPa

$$\Delta B_{c2}^{\text{unload}} \approx 0.5 \text{ T}$$

Measured I_c^{unload} vs expected degradation from residual stress

(open blue points) (solid red stars)



The observed permanent degradation of I_c after unload from σ up to 240 MPa originates mainly from the residual stress on Nb_3Sn due to the plastic deformation of Cu

The effect of cracks seems negligible up to very high transverse stress values

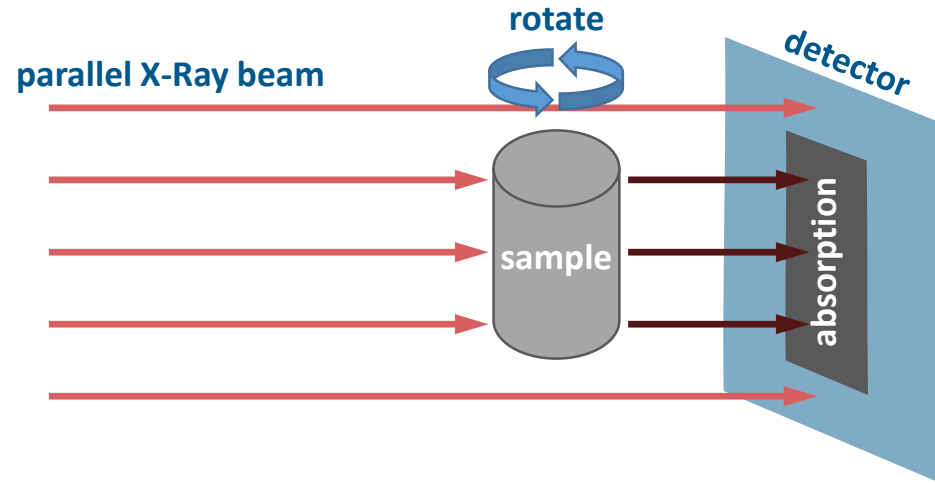
X-ray tomography and Neural Networks for crack detection

An independent confirmation of the conclusions

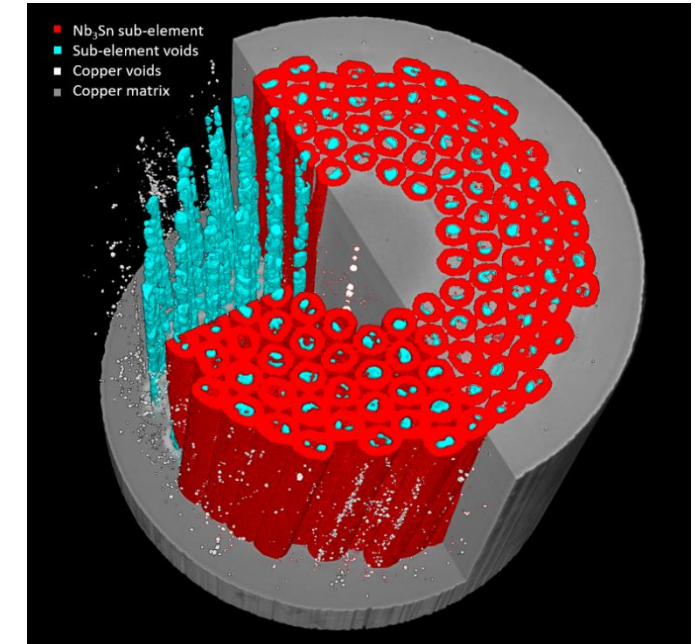
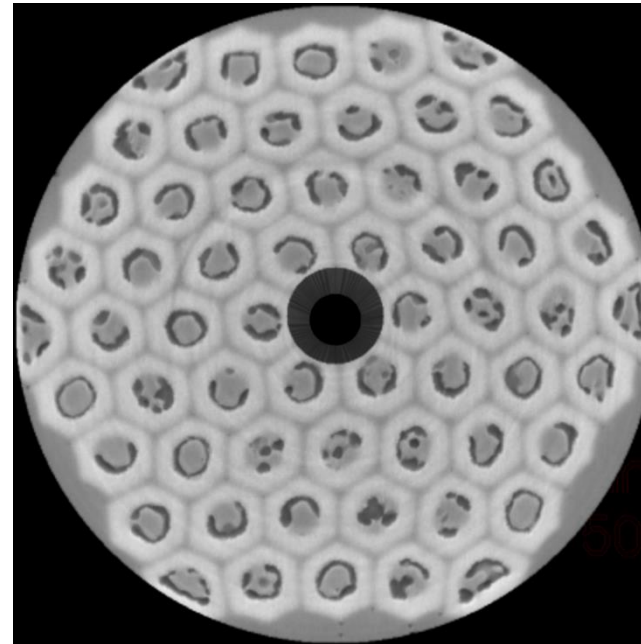


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- X-ray photon energy = 80 keV
- 360° rotation of the sample
- 10'000 projections
- 2560 x 2160 pixels
- 0.57 μm /pixel resolution



A novel, non-destructive and non-invasive method to investigate the internal structure of high-performance Nb₃Sn wires combines **X-ray microtomography** with **machine-learning algorithms**



Marta MAJKUT
Alexander RACK

T. Bagni *et al.*, Sci. Reports **11** (2021) 7767 DOI: [10.1038/s41598-021-87475-6](https://doi.org/10.1038/s41598-021-87475-6)

X-ray tomography and Neural Networks for crack detection

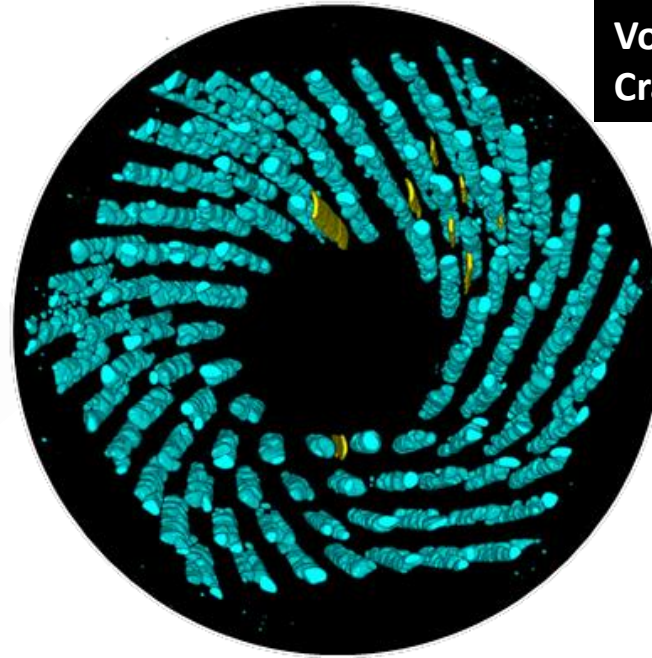
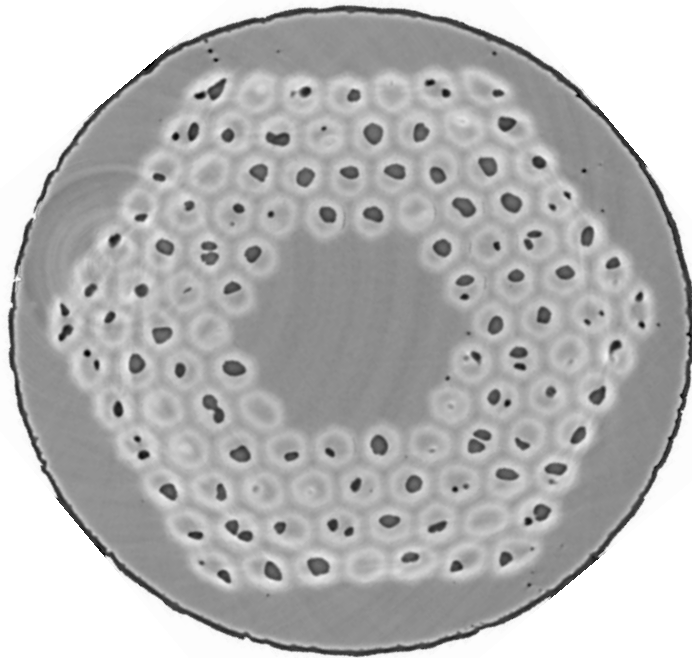
An independent confirmation of the conclusions



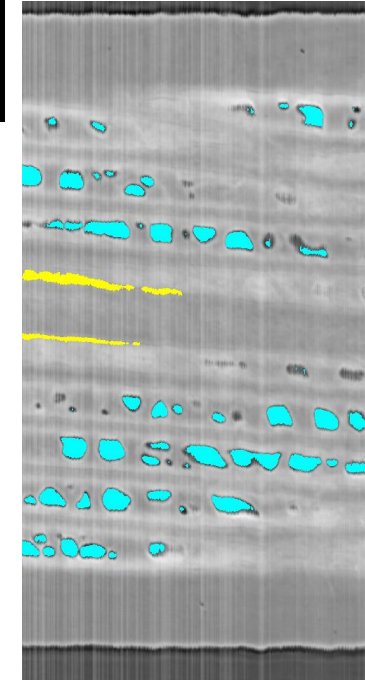
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Voids in cyan
Cracks in yellow



An analysis based on Convolutional Neural Networks was performed on the tomographic scan of the exact same sample used for the I_c vs σ test, after unload from 240 MPa

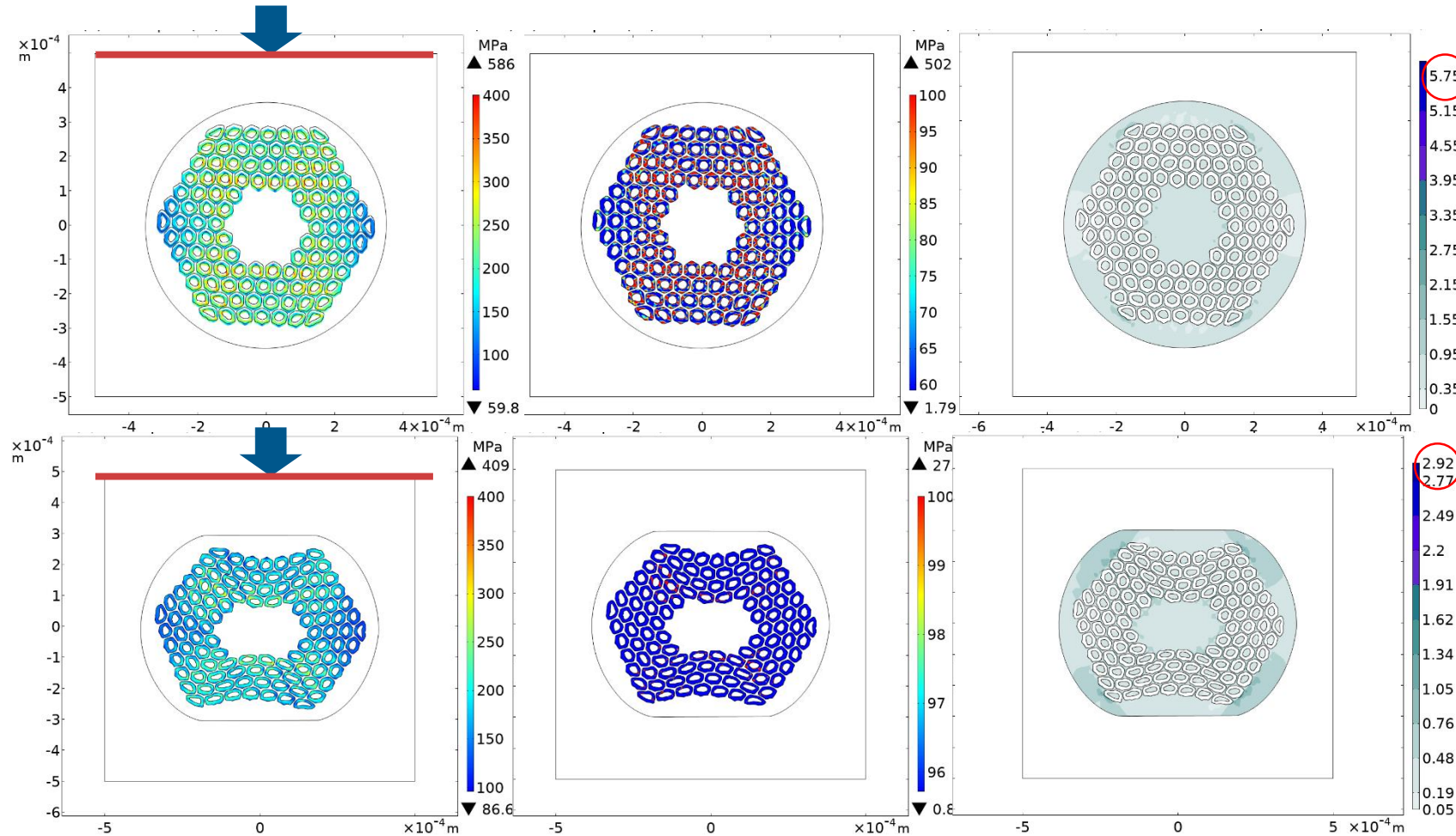
Very few cracks were detected, none of them interrupting the subelements and thus responsible for the measured degradation by 15% of I_c



Ciro
CALZOLAIO

2D FE electromechanical models with

I_c degradation from Cu plasticization and consequences of wire rolling



Von Mises stress in Nb_3Sn
under a load of 30 kN

Von Mises stress in Nb_3Sn
after unload from 30 kN

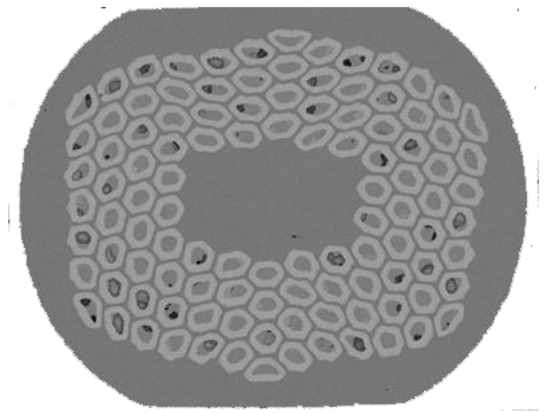
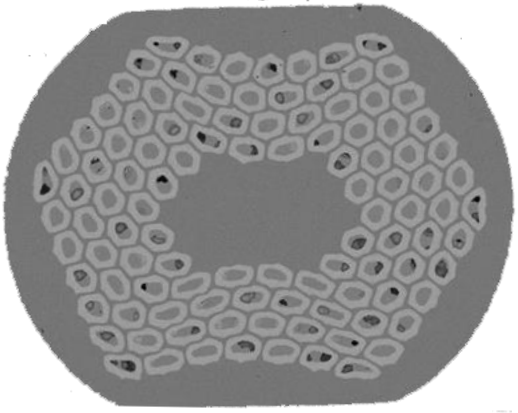
Plastic deformation of Copper
after unload from 30 kN

Simulations support the experimental evidence that 15% rolling is associated with a slight improvement of the tolerance to transverse stress

This is due to a better redistribution of the load

Summary and outlook

- Tolerance to stress is an issue as important as high critical current density for the conductors to be used in Nb₃Sn-based accelerator magnets
- Experiments show that up to 240 MPa the permanent **degradation of I_c** is dominated by the **residual stress**. Surprisingly, the **effect of cracks seems negligible**
- With the goal of providing new insights into the electromechanical modelling of the wires, a **tool combining tomography and machine learning** was developed to investigate the internal structure of the wires
- **FE simulations** represent a valuable tool for the development of tailored wire designs with improved stress tolerance
- There are many ideas to explore and a strong temptation to **launch a WireNum** project combining FE and machine learning
- Discussions are ongoing with CERN to start also the **activities of WireChar on HTS in the frame of the HFR R&D**



Thank you for the attention !

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